



12-27-2001



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Packet No.: 52201-0605

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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

**Tatsuhiro Sato, Nobumasa Yoshida,
Akira Fujinoki, Kyoichi Inaki,
Tomoyuki Shirai**

Additional names(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: 10/24/01, 10/31/01, 11/7/01

2. Name and address of receiving party(ies):

Name: **Heraeus Quarzglas GmbH & Co. KG**

Internal Address: _____

Street Address: **Quarzstrasse 8**

63450 Hanau, Germany

City: _____ State: _____ ZIP: _____

Additional name(s) & address(es) attached? ☒ Yes ☐ No

4. Application number(s) or patent numbers(s):

If this document is being filed together with a new application, the execution date of the application is: _____

A. Patent Application No.(s)

09/935,334

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **Andrew L. Tiajolloff, Esq.**

Internal Address: _____

Street Address: **330 Madison Avenue**

12/26/2001 ANMED1 00000041 501659 09935334

01 FC:581 40.00 CH

City: **New York** State: **NY** ZIP: **10017**

6. Total number of applications and patents involved: **1**

7. Total fee (37 CFR 3.41):.....\$ **40.00**

- ☒ Enclosed - Any excess or insufficiency should be credited or debited to deposit account
☐ Authorized to be charged to deposit account

8. Deposit account number:

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Andrew L. Tiajolloff Reg. No. **31,575**

Name of Person Signing

Signature

DEC. 5, 2001

Date

Total number of pages including cover sheet, attachments, and document: **4**

ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

QUARTZ GLASS BODY HAVING IMPROVED RESISTANCE AGAINST PLASMA CORROSION, AND METHOD FOR PRODUCTION THEREOF,

for which a United States patent application was filed on August 22, 2001 and assigned Serial No. 09/935,334.

AND WHEREAS,

Heraeus Quarzglas GmbH & Co. KG, a German corporation with offices at Quarzstrasse 8, 63450 Hanau, Germany,

and

Shin-Etsu Quartz Products Co., Ltd., a Japanese corporation with offices at 22-2, Nishi-Shinjuku 1-chome, Shinjuku-ku, Tokyo 160-0023, Japan,

(hereinafter together referred to as ASSIGNEE) are desirous of acquiring all, interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America, and any official of any country whose duty is to issue patents on applications as described above, to issue all Letters Patent in the United States of America and any other country to said ASSIGNEE, as the assignees of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial

Number: _____, Filing Date: _____

This assignment executed on the dates indicated below.

November 7, 2001
Date

Tatsuhiro Sato
TATSUHIRO SATO

October 24, 2001
Date

Nobumasa Yoshida
NOBUMASA YOSHIDA

October 24, 2001
Date

Akira Fujinoki
AKIRA FUJINOKI

October 24, 2001
Date

Kyoichi Inaki
KYOICHI INAKI

October 31, 2001
Date

Tomoyuki Shirai
TOMOYUKI SHIRAI